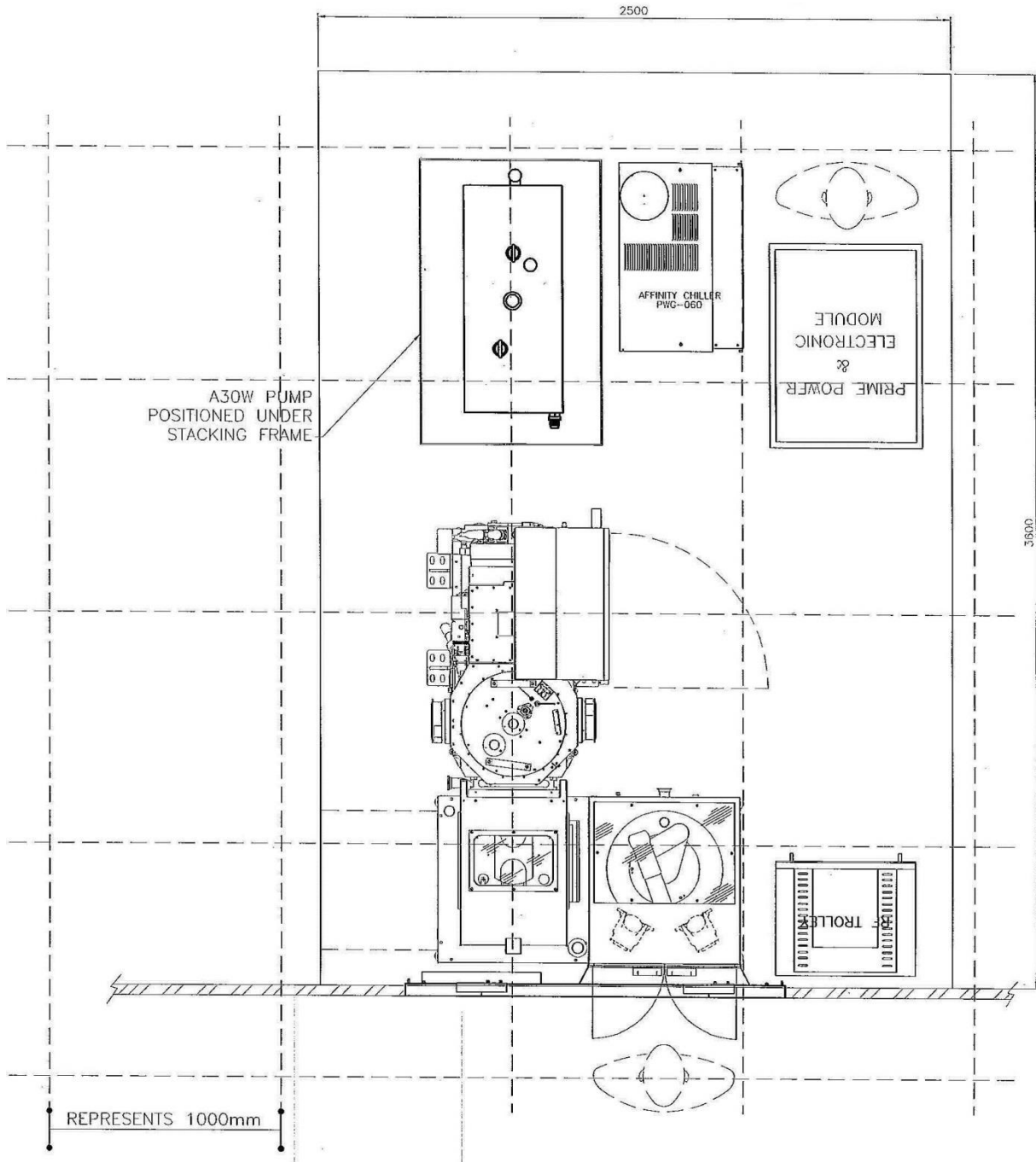


# STS MACS ICP<sup>HR</sup> Etch System

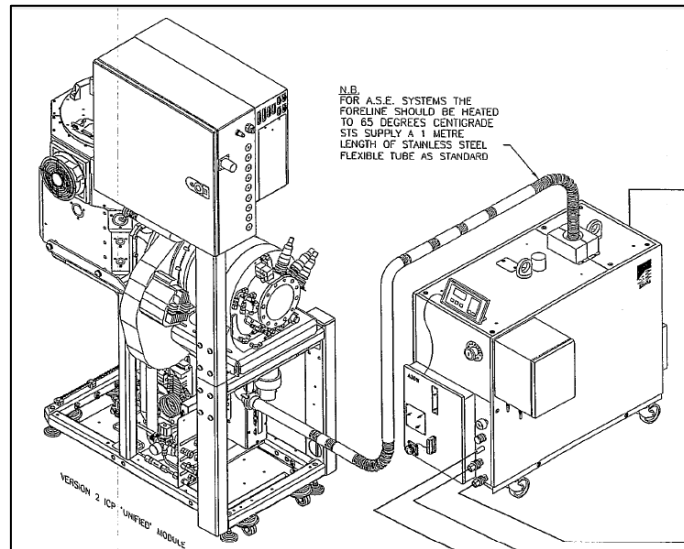
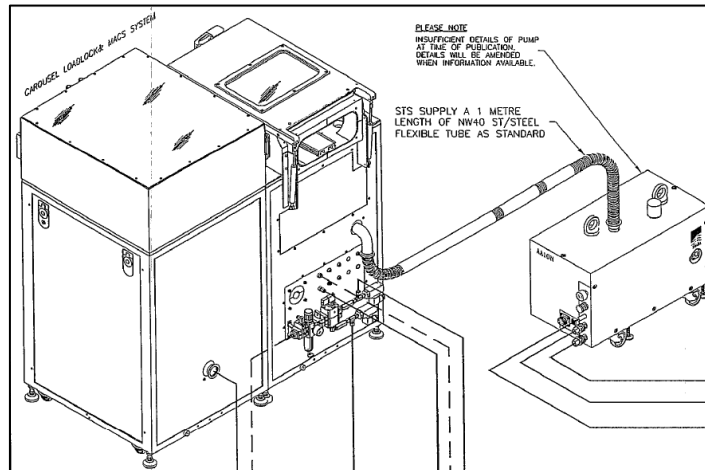


FOOTPRINT LAYOUT OF MACS ICP (HR)

# EQUIPMENT DATASHEET

Item List	Description
Manufacturer:	STS
Model:	MACS ICP <sup>HR</sup>
Wafer Size:	150/200mm. The current status is mainly 200mm.
Tool Condition:	Used
Chamber Quantity:	1 Chamber
Volts / Hz/Ph:	208 Volts / 60 Hz ,40 Amps/phase
Vintage:	2001

## ➤ System General View :



# EQUIPMENT DATASHEET

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## ➤ System Components and Configuration

1. Advanced Silicon Etch (ASE) with Bosch process
2. HR Chamber for High Rate Etch
3. Set up for 200mm wafer (150mm-200mm capable)
4. MACs Loader for Cassette to Cassette operation (2 load stations)
5. Carousel vacuum load lock
6. Helium Backside Cooling (HBC)
7. Clamp Type: Standard WTC

## ➤ RF Generators:

1. Coil RF Power : Advanced Energy RFG3001,3KW
2. Platen RF Power : ENI ACG-3B 13.56MHZ, 300W

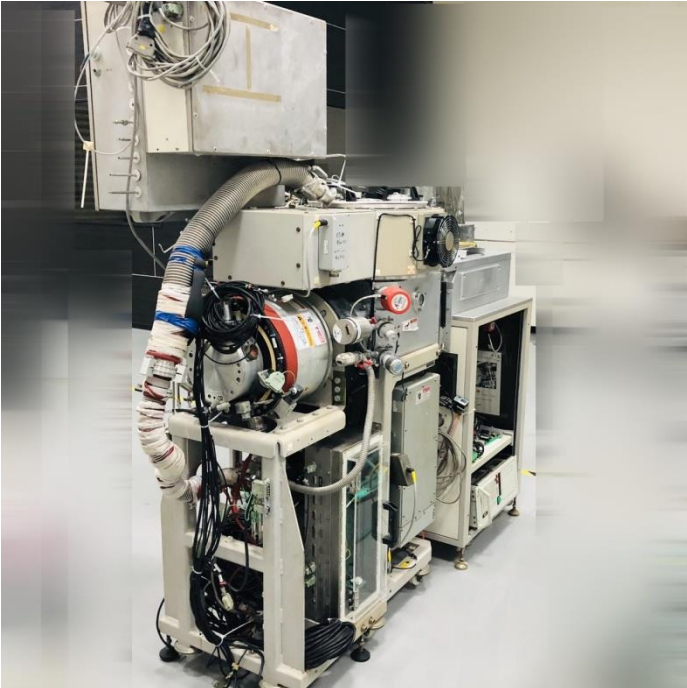
➤ Gases:  $C_4F_8$ (200 sccm) 、  $SF_6$ (1000 sccm) 、  $O_2$ (200 sccm) 、 Ar (50 sccm)

## ➤ Vacuum System

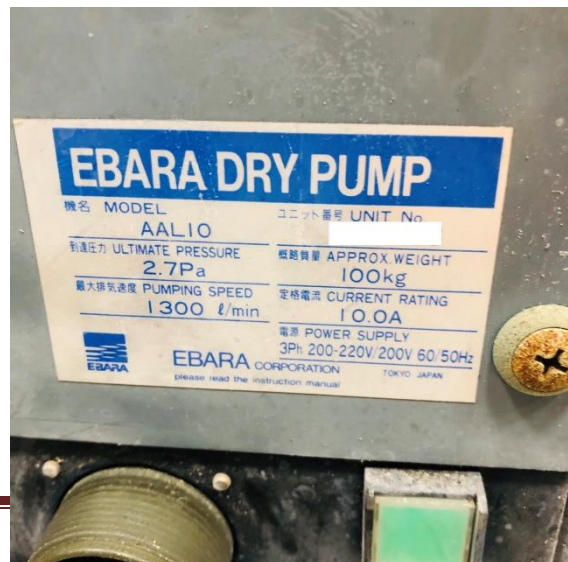
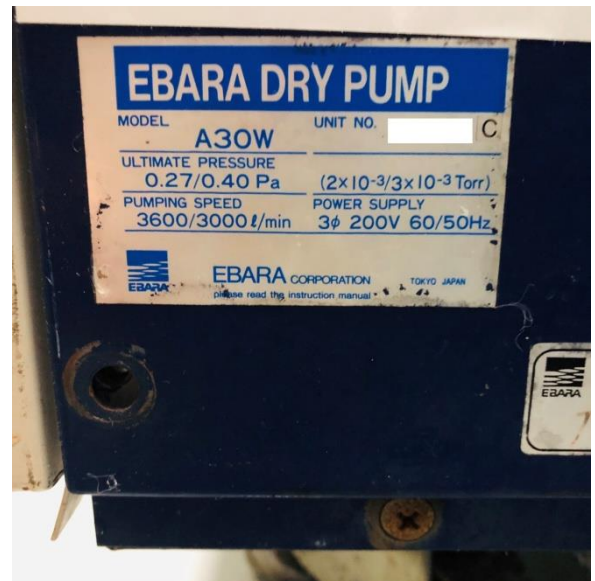
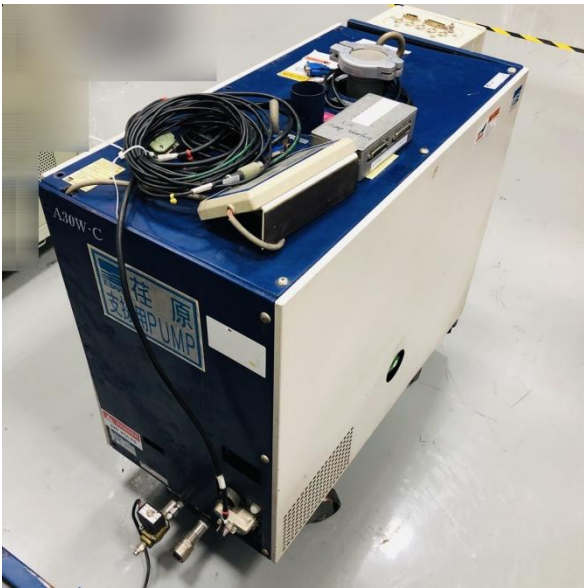
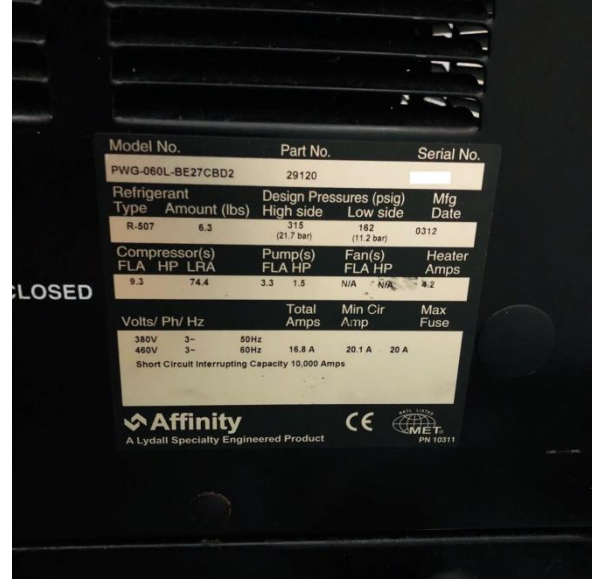
1. Load Lock Pump: EBARA AAL10
2. Chamber Pump: EBARA A30W

➤ Chiller: Affinity PWG-060L-BE27CBD2

## Photos:



# EQUIPMENT DATASHEET





# EQUIPMENT DATASHEET

